

### Amendments to the Claims

This listing of claims replaces all prior versions and listings of claims in the application.

#### Listing of Claims:

1. (Currently Amended) A system for channeling high frequency signals within an electronic device, comprising:

a midplane circuit board;

a midplane chassis shield disposed adjacent to said midplane circuit board;

an interface module suitable for being coupled to said midplane circuit board through said midplane chassis shield, the interface module including an EMC seal, an interface module container and an interface circuit board, said interface circuit board being substantially contained within said interface module container;

an interface connector suitable for coupling said interface circuit board to said midplane circuit board, said interface connector including a first connector half coupled to said interface circuit board and including an interface connector shield and a second connector half coupled to said midplane circuit board; and

a gasket disposed between said interface connector shield and said interface module container;

wherein said interface connector shield, midplane circuit board, midplane chassis shield and interface module cooperate for providing a low impedance tunnel for channeling high frequency signals to ground.

2. - 5. (Cancelled)

6. (Currently Amended) The system according to claim 31, wherein said connector further comprises at least one logic pin and at least one ground shield pin.

7. (Currently Amended) The system according to claim 21, wherein said interface module container further comprises at least one suspension ground spring suitable for substantially holding said interface module in said electronic device.

8. (Original) The system according to claim 1, wherein said midplane chassis shield comprises at least one guide for securing said interface module to said midplane chassis.

9. (Cancelled)

10. (Currently Amended) An electronic device, comprising:  
a housing;  
a midplane circuit board;  
a midplane chassis shield disposed adjacent to said midplane circuit board;  
an interface module suitable for being coupled to said midplane circuit board through said midplane chassis shield, the interface module including an EMC seal, an interface module container and an interface circuit board, said interface circuit board being substantially contained within said interface module container;  
an interface connector suitable for coupling said interface circuit board to said midplane circuit board, said interface connector including a first connector half coupled to said interface circuit board and including an interface connector shield and a second connector half coupled to said midplane circuit board; and  
a gasket disposed between said interface connector shield and said interface module container;  
wherein said interface connector shield, midplane circuit board, midplane chassis shield and interface module cooperate for providing a low impedance tunnel for channeling high frequency signals to ground.

11. – 14. (Cancelled)

15. (Currently Amended) The electronic device according to claim ~~14~~10, wherein said connector further comprises at least one logic pin and at least one ground shield pin.

16. (Currently Amended) The electronic device according to claim ~~14~~10, wherein said interface module container further comprises at least one suspension ground spring suitable for substantially holding said interface module in said electronic device.

17. (Original) The electronic device according to claim 10, wherein said midplane chassis shield comprises at least one guide for securing said interface module to said midplane chassis.

18. – 20. (Cancelled)